PRODUCT CHANGE NOTICE

1. TITLE
HFB25HJ20, Ultra-Fast Discrete Diode

2. DOCUMENT NUMBER
FV5-C-11-004

3. DATE
February 23, 2011

4. MANUFACTURER AND ADDRESS
International Rectifier
205 Crawford Street
Leominster, MA 01453

5. MANUFACTURER PART NUMBER
See below for IR Part Numbers

6. BASE PART
NA

7. NATIONAL STOCK NUMBER (NSN)
NA

8. CAGE
69210

9. EFFECTIVE DATE
February 22, 2011

10. GOVERNMENT NUMBER
NA

11. POINT OF CONTACT
Manufacturer’s Representative or
Customer Service Representative (978) 534-5776

12. DRAWING NUMBER
NA

13. SPECIFICATION NUMBER
MIL-PRF-19500

14. PRODUCT CHANGE
This GIDEP PCN is to announce the addition of Toshiba XE13-B9144 (33-0275-06B) die coat to the following International Rectifier Part No.

HFB25HJ20
HFB25HJ20SCS
HFB25HJ20SCX
HFB25HJ20SCV

Description: 200V 25A Hi-Rel Ultra-Fast Discrete Diode in a SMD-0.5 package.

Reason for Change: Arcing can occur at high voltage as a result of surface charge build-up in the termination area. To prevent arcing, IR will apply a controlled amount of silicone based coating to the FRED die surface. The die coat acts as passivation to effectively suppress any arcing in the termination. This change will extend the die coat application from the 400V, where it is being used currently, to the 200V FRED product.

Impact of Change: No effect to form, fit, or function. Additional package weight of less than 3mg.

Qualification: As this process is qualified on higher voltage products, qualification is not required per MIL-PRF-19500. However, IR is performing GRP A, B, C, and E (partial) per MIL-PRF-19500 for internal validation.